



Device Material Content

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Package: 64 ucfBGA
Total Device Weight 22.93 Milligrams

Package Code:

UMG64

Products:

LIF-MD6000 (Crosslink)

Assembly: ASET
Size (mm): 3.5 x 3.5
Lead pitch (mm): 0.4
MSL: 3
Reflow max (°C): 260

January-19

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	22.79%	5.225	22.79%	5.2250	Silicon chip	7440-21-3	100.00%	Die size: 2.51 x 2.56mm
Substrate	16.64%	3.816	6.41% 0.30% 0.10% 0.10% 0.06% 0.24% 9.43% 0.01%	1.4699 0.0694 0.0219 0.0219 0.0146 0.0548 2.1612 0.0023	Laminate* Barium Sulfate Talc Phosphin oxide derivative Silica Epoxy Resin Copper (Cu) OSP	Trade secret 7727-43-7 14807-96-6 Trade secret Trade secret Trade secret 7440-50-8 Trade secret	38.52% 1.82% 0.57% 0.57% 0.38% 1.44% 56.63% 0.06%	CCL-HL 832NS Solder mask PFR800 Aus410
Repassivation polyimide	0.10%	0.024	0.06% 0.01% 0.00% 0.04%	0.0132 0.0012 0.0001 0.0095	N-Methyl-2-pyrrolidone Proprietary Monomer Methanol Non regulated ingredients	872-50-4 Trade secret 67-56-1 Trade secret	55.00% 5.00% 0.50% 39.50%	HD4000E
UBM	0.07%	0.016	0.01% 0.06%	0.0032 0.0128	Titanium (Ti) Copper (Cu)	7440-32-6 7440-50-8	20.25% 79.75%	
Bump	5.94%	1.363	4.80% 0.09% 0.84% 0.22%	1.1002 0.0202 0.1922 0.0506	Tin (Sn) Silver (Ag) Nickel (Ni) Copper (Cu)	7440-31-5 7440-22-4 7440-02-0 7440-50-8	80.72% 1.48% 14.1% 3.71%	
Mold Compound	37.53%	8.605	2.06% 1.88% 0.94% 0.19% 26.64% 5.82%	0.4733 0.4303 0.2151 0.0430 6.1096 1.3338	Epoxy Resin Phenol Resin Metal Hydroxide Carbon Black Silica (Amorphous) A Silica (Amorphous) B	Trade secret Trade secret Trade secret 1333-86-4 60676-86-0 7631-86-9	5.50% 5.00% 2.50% 0.50% 71.00% 15.50%	EME-G311SA Type C
Solder Balls	16.93%	3.881	16.63% 0.20% 0.08% 0.01%	3.8131 0.0466 0.0194 0.0019	Tin (Sn) Silver (Ag) Copper (Cu) Nickel (Ni)	7440-31-5 7440-22-4 7440-50-8 7440-02-0	98.25% 1.20% 0.50% 0.05%	Sn98.25/Ag1.2/Cu0.5/Ni0.05

Notes: * 0.06% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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